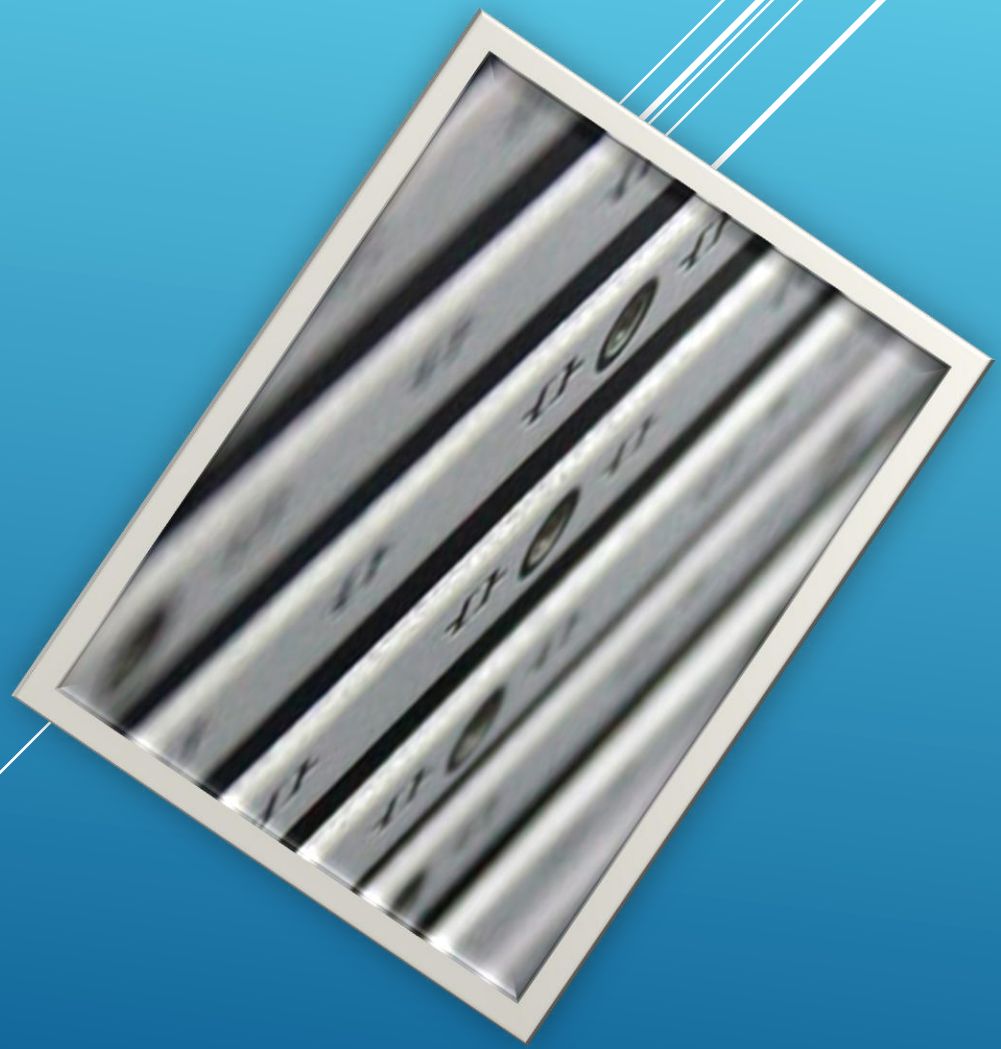
GIA TZOONG ENTERPRISE CO., LTD (Taiwan Factory)
GIA TZOONG LTD. (shenzhen)

PSC

investor conference

2026



Agenda

- Introduction
- **Consolidated Statements of Comprehensive Income**
- Research and development expenses
- Operational Overview
- Q&A

INTRODUCTION

- Date of incorporation: September 19, 1988
- Date of listed on Taiwan OTC market：June 23,1999
- Capital：NTD 0.775 billion
- Number of staffs：271
- Main business transaction：Manufacturing of PCB
- Address : No. 39-4, Xingbang Rd., Taoyuan District, Taoyuan City

2.CONSOLIDATED STATEMENTS OF COMPREHENSIVE INCOME

(1) PSC's Income Statement

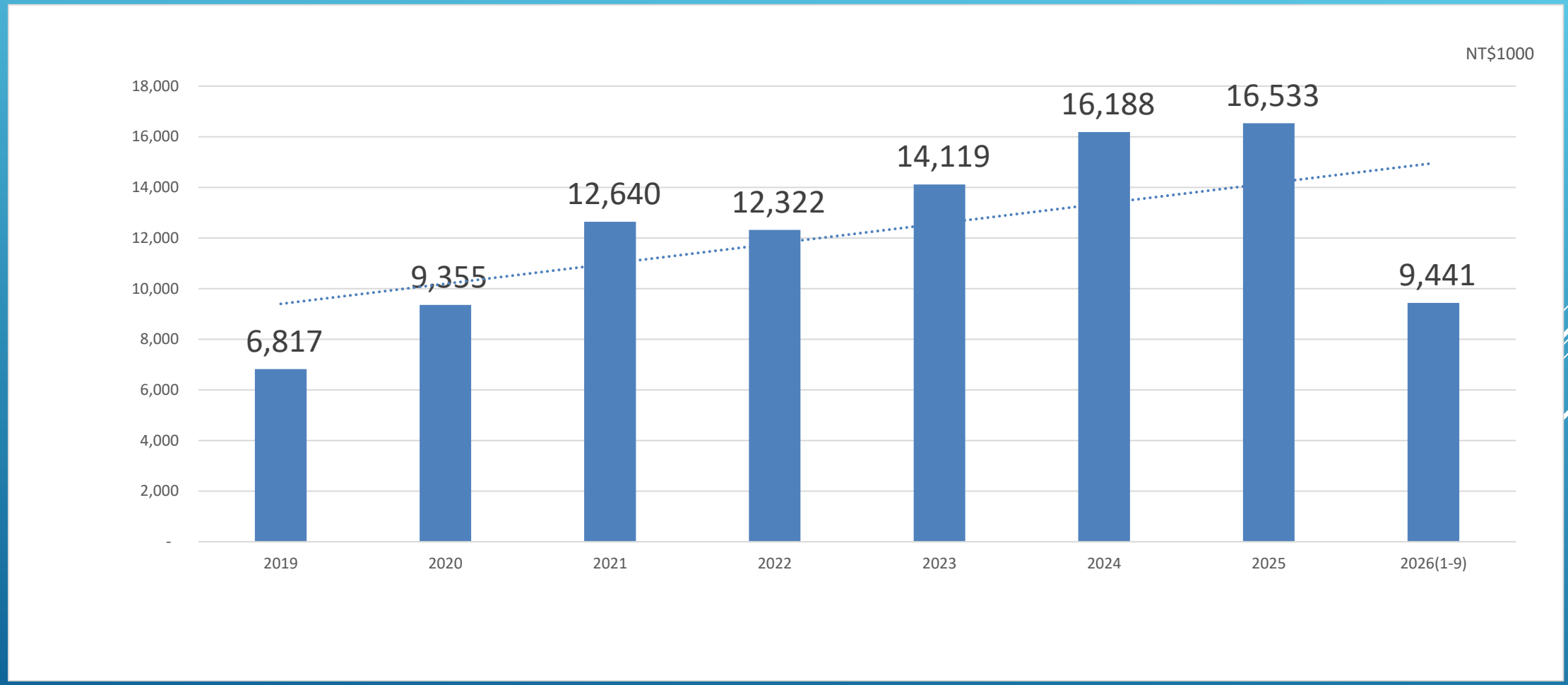
NT$1000

Item	2026/1-9	2025/1-9	%
Operating revenues	499,034	341,511	46
Operating cost	(472,044)	(407,400)	16
Gross operating loss	26,990	(65,889)	(141)
Operating expenses	(72,003)	(64,767)	11
Net operating loss	(45,013)	(130,656)	(66)
Non-operating income and expenses	18,421	(6,736)	(373)
Loss from continuing operations before income tax	(26,592)	(137,392)	(81)
Income tax expenses	1,100	1,442	(24)
Net profit	(25,492)	(135,950)	(81)

(2) PSC's Q1–Q3 Income Statement

Item	2026Q1	2026Q2	2026Q3
Operating revenues	118,960	167,633	212,441
Operating cost	(130,842)	(154,537)	(186,665)
Gross operating loss	(11,882)	13,096	25,776
Operating expenses	(24,408)	(22,763)	(24,832)
Net operating loss	(36,290)	(9,667)	944
Non-operating income and expenses	14,628	4,779	(986)
Loss from continuing operations before income tax	(21,662)	(4,888)	(42)
Income tax expenses	(2,071)	(588)	3,759
Net profit	(23,733)	(5,476)	3,717

3.RESEARCH AND DEVELOPMENT EXPENSES



PCB & Substrate Technology Roadmap

Technology Direction	Short-Term Focus	Mid-to-Long-Term Direction
HDI / High-Layer Count (HLC) PCB	• Enhance process capabilities for high layer counts, microvias, and fine lines/spaces	• Advance 20+ layer HLC PCB manufacturing processes • Develop Any-Layer structures and stacked/staggered multi-step microvia processes • Improve layer-to-layer registration accuracy
High-Speed Material PCB	• Evaluate low-loss high-speed materials • Verify hybrid lamination processes for dissimilar materials	• Evaluate M8+ grade high-speed material applications • Develop hybrid lamination technology for PTFE and FR-4 • Expand high-frequency, high-speed transmission PCB applications
MCPCB / Ceramic Substrate	• Design high-thermal-dissipation structures • Develop ceramic-to-metal bonding technologies	• Advance AMB / DBC ceramic substrate bonding technologies • Develop thermal dissipation substrates for high-power modules • Develop high-reliability metal-ceramic composite structures
Component-Embedded Board (CIB)	• Design embedded structures • Integrate manufacturing processes and verify reliability	• Develop CIB products for LED lighting modules and power modules • Develop CIB applications for RF array antennas and optical communication modules

OPERATIONAL OVERVIEW

1.DBC
(1) Number of potential customers: 11
(2) Number of customers undergoing verification: 4
(3) Number of customers in mass production: 2

2.FR4: New form-embedded(Embedded ceramics and electronic components)
(1) Number of potential customers: 8
(2)Number of customers under collaborative development: 8
(3)Number of customers in mass production: 1

Q&A

THANKS